PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6875349

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIUN-SHENG YANG	07/27/2021
HSING-HAO CHEN	07/27/2021

RECEIVING PARTY DATA

Name:	WINBOND ELECTRONICS CORP.
Street Address:	NO. 8 KEYA 1ST RD., DAYA DISTRICT, CENTRAL TAIWAN SCIENCE PARK.
City:	TAICHUNG CITY
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17402087

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe Mckinney Muncy/
DATE SIGNED:	08/20/2021

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Jiun-Sheng YANG and Hsing-Hao CHEN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR MEMORY STRUCTURE AND METHOD FOR FORMING THE SAME

Filed: 13 August 2021 Serial No. 17402087

Executed on:

WHEREAS, Winbond Electronics Corp. of No. 8 Keya 1st Rd., Daya District, Central Taiwan Science Park, Taichung City, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, and the entire rights, title and interest in and to any and all foreign patents and applications for any invention described in said U.S. patent applications, in any and all countries foreign to the U.S., including all rights of priority arising from them, and all the rights and privileges under any and all forms of protection, including patents, that may be granted in said countries foreign to the U.S. for them, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

July 27, 2021 Jiun Sheng Yang
Date Name: Jiun-Sheng YANG

July 27, 2021 Hsing Hao CHEN
Date Name: Hsing-Hao CHEN

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING APPLICATION DATA SHEET (37 CFR 1.76)

Title of the Invention: SEMICONDUCTOR MEMORY STRUCTURE AND METHOD FOR FORMING THE SAME

As the below named inventor, I hereby declare that:

This declaration is directed to the attached application, or, if the application is not attached hereto, United States application or PCT international application number ________________________ filed on ________________________.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor's Name⇨ Inventor: Jiun-Sheng YANG Date: July 27, 2021

Inventor's Signature⇨ Signature: Jiun Sheng Yang

☑ Additional inventors are being named on the 1 supplemental sheet(s) attached hereto.